NTC

Material Data Sheet

Product Class	**NTC Thermistor B57276K* with Rast 5 connector**
Date	**27.07.2022**
IMDS ID if available	
Version	**05**

Product Part (IMDS: semi component)	**Material Class** (IMDS: Material)	**Material (Classification)** VDA 231	**Substance**	TMPS**) [wt%]	**CAS if applicable**	**typical mass of material [wt-%]**	**Traces see 1)**
Active Part	Ceramic	3B	Mn_3O_4 NiO Co_3O_4 Dopants*)	64 17 15 4	1317-35-7 1313-99-1 1308-06-1	0,3	
Termination	Noble Metal	1D	Ag Glass frit (Pb-B-silicate)	95 5	7440-22-4	0,02	
Solder	Heavy Metal	1C	Pb Sn Ag	97 1 2	7439-92-1 7440-31-5 7440-22-4	0,38	
Leads	Iron and Steel	1A	Fe	100	7439-89-6	0,45	
	Heavy Metal	1C	Cu	100	7440-50-8	0,3	
	Heavy Metal	1C	Sn	100	7440-31-5	0,05	
Coating	Duromer	2D	Epoxy Brominated epoxy Sb_2O_3 SiO_2	37,5 11 2,5 49	25068-38-6 40039-93-8 1309-64-4 60676-86-0	0,4	
	Elastomer	2B	Silicone rubber	100		0,6	
Connector	Heavy Metal	1C	Cu Zn	65 35	7440-50-8 7440-66-6	9	
	Heavy Metal	1C	Ni	100	7440-02-0	0,1	
	Heavy Metal	1C	Sn	100	7440-31-5	0,2	
	Thermoplast	2A	Polybutylenterephthalate (PBT) incl. brominated compound***) and Sb_2O_3	100		20	
Encapsulation	Duromer	2D	Epoxy incl. brominated compound***) and Sb_2O_3	100		32	
Solder	Heavy Metal	1C	Sn Cu	99 1	7440-31-5 7440-50-8	0,5	
Housing	Iron and Steel	1A	Fe Cr Ni Others*)	69 18 10 3	7439-89-6 7440-47-3 7440-02-0	35,7	
					Sum in total:	100	

sizes [mm]	weight range [g]	part numbers:
ϕ10 x 44,5	8,4	types B57276K* with Rast 5 connector

Not Part of a Product Class

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*) others: (not declarable or prohibited substances acc. GADSL)

**) typical mass percentage of substance

***) no PBB, PBDE, HBCDD

Important remarks:

1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated.

2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (☑ valid ☐ not valid **)**

☐ **no exemptions;**

☐ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

☐ Exemption 6 (b): Lead as an alloying element in aluminum containing up to 0,4 % lead by weight;

☐ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

☑ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

☑ Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

☐ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;

☐ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

☐ Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

☐ Other Exemption than above .....